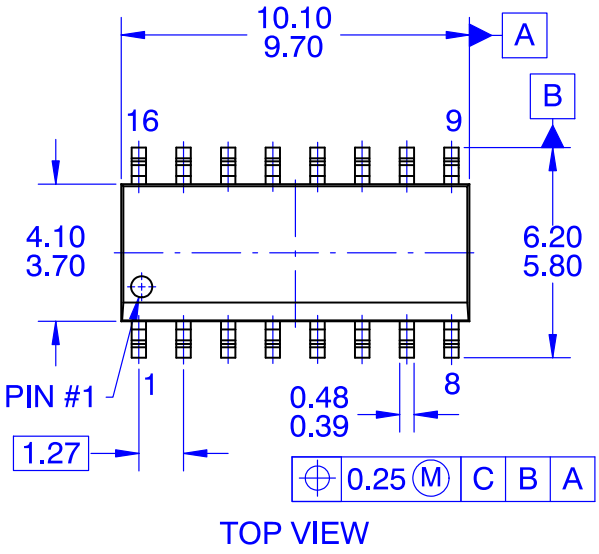
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

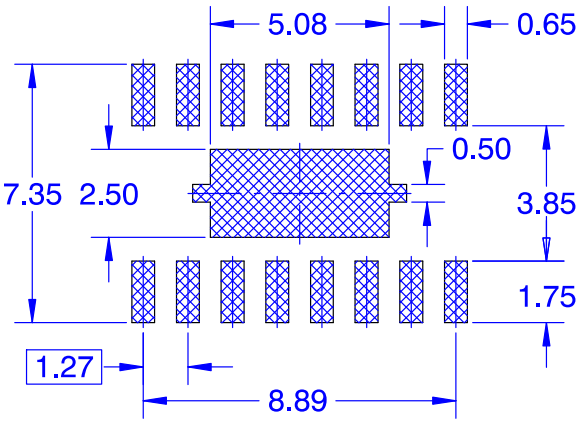
ON Semiconductor®

SOIC16 N EP
CASE 751EK
ISSUE O

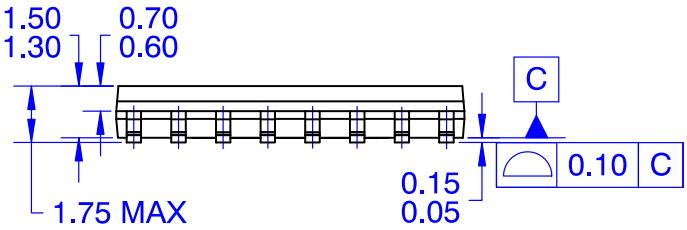
DATE 30 SEP 2016



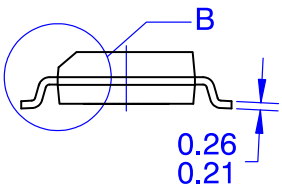
TOP VIEW



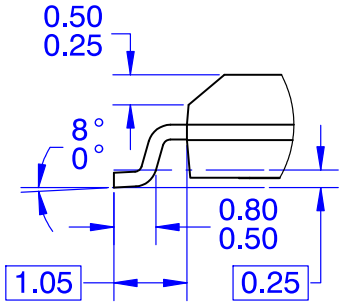
LAND PATTERN RECOMMENDATION



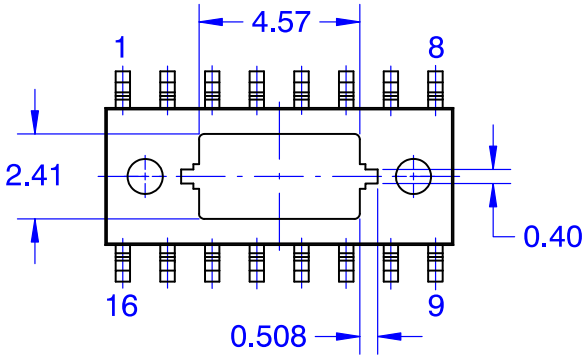
FRONT VIEW



SIDE VIEW



DETAIL B
SCALE 2:1



BOTTOM VIEW

NOTES:
A. NO INDUSTRY STANDARD APPLIES TO THIS PACKAGE
B. ALL DIMENSIONS ARE IN MILLIMETERS
C. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS

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